



Material Content Data Sheet



Sales Product Name		ESD0P4RFL E6327		Issued		19. July 2018		
MA#		MA000432684						
Package		PG-TSLP-4-7		Weight*		0.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.09		897	
	noble metal	gold	7440-57-5	0.003	0.35		3477	
	inorganic material	silicon	7440-21-3	0.041	4.24	4.68	42432	46806
leadframe	non noble metal	nickel	7440-02-0	0.265	27.58	27.58	275841	275841
wire	noble metal	gold	7440-57-5	0.008	0.85	0.85	8455	8455
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		313	
	organic material	carbon black	1333-86-4	0.006	0.63		6268	
	plastics	epoxy resin	-	0.081	8.46		84610	
	inorganic material	silicondioxide	60676-86-0	0.515	53.55	62.67	535552	626743
leadfinish	noble metal	gold	7440-57-5	0.014	1.41	1.41	14052	14052
plating	noble metal	gold	7440-57-5	0.027	2.81	2.81	28103	28103
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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